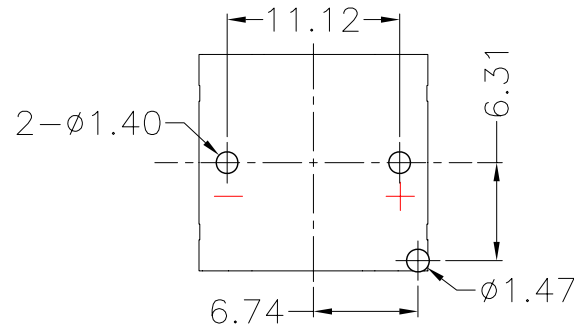
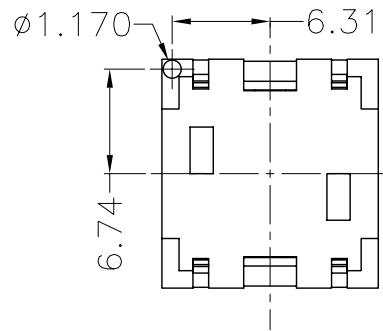
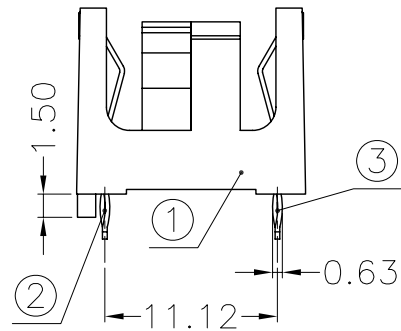
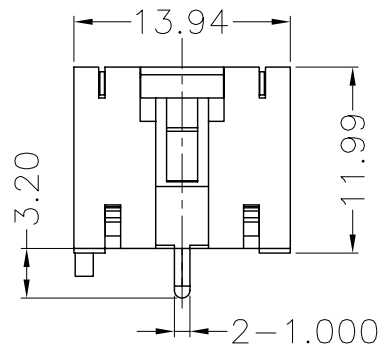
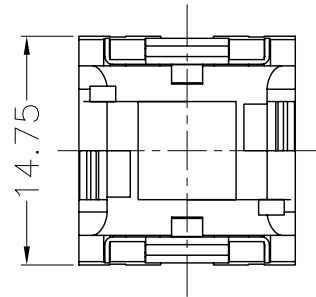




REV.	ECN NO.	REVISED	DATE



PCB Layout Diagram  
Top View

1.MATERIAL:

- a.HOUSING:PPA
- b.CONTACT:PHOSPHOR BRONZE  
(SURFACE PLATING:Au1u")

SEE ORDERING INFORMATION

2.ELECTRIC:

- a.CONTACT RESISTANCE: 30 MILLIOHMS MAX
- b.INSULATION RESISTANCE: 1000 MEGA OHMS MIN
- c.DIELECTNIC VOLTAGE: 500V AC ONE SEC LEVEL
- d.OPERATING TEMPERATURE: -25°C~ +85°C

ORDERING INFORMATION

**BS-09-A\*\*\*002**

电池座系列

BS-09系列

DIP 90° TYPE

PLATING:  
A-Au1U"  
J-Ni100U"~120U"  
K-Sn100U"~120U"

MATERIAL:  
1A-PBT BLACK  
1B-PA66 BLACK  
2A-PPA BROWN  
2B-PPA BLACK  
3A-PPS BROWN  
3B-PPS BLACK  
4A-LCP WHITE  
4B-LCP BLACK



3	TERMINAL(-)	1	PHOSPHOR BRONZE, T=0.30mm	Gold Plating and Ni Under-Plating
2	TERMINAL(+)	1	PHOSPHOR BRONZE, T=0.30mm	Gold Plating and Ni Under-Plating
1	HOUSING	1	PPA	BLACK
NO.	PART NAME	Q'TY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES		<b>MYOUNG 美阳</b> <a href="http://www.meiyangdz.com">www.meiyangdz.com</a>	
DECIMALS: X :±0.30 X.X :±0.25 X.XX :±0.20 X.XXX :±0.10	ANGLES: X :±1° X.X :±0.5°	DSND YangFeng	DATE 2017-07-13
WEIGHT: 1.91g		CHKD ZhouRuicai	DATE 2017-07-13
SHEET 1 OF 1		APVD XueShunyong	DATE 2017-07-13
UNIT: mm	REV.: A/0	SCALE: 2:1	VIEW:
OBJECT: MY	DRAW NO.:MY-CP-0084	TITLE: BS-2AG13-9 DIP	PART NO.: BS-09-A2BA002